# Device Modeling Report

COMPONENTS: Power MOSFET (Model Parameter)
PART NUMBER: TPCM8002-H
MANUFACTURER: TOSHIBA
Body Diode (Model Parameter)

**Bee Technologies Inc.**

Circuit Configuration
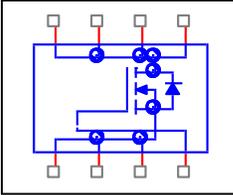
MOSFET MODEL

| Pspice model parameter	Model description
LEVEL	
L	Channel Length
W	Channel Width
KP	Transconductance
RS	Source Ohmic Resistance
RD	Ohmic Drain Resistance
VTO	Zero-bias Threshold Voltage
RDS	Drain-Source Shunt Resistance
TOX	Gate Oxide Thickness
CGSO	Zero-bias Gate-Source Capacitance
CGDO	Zero-bias Gate-Drain Capacitance
CBD	Zero-bias Bulk-Drain Junction Capacitance
MJ	Bulk Junction Grading Coefficient
PB	Bulk Junction Potential
FC	Bulk Junction Forward-bias Capacitance Coefficient
RG	Gate Ohmic Resistance
IS	Bulk Junction Saturation Current
N	Bulk Junction Emission Coefficient
RB	Bulk Series Resistance
PHI	Surface Inversion Potential
GAMMA	Body-effect Parameter
DELTA	Width effect on Threshold Voltage
ETA	Static Feedback on Threshold Voltage
THETA	Modility Modulation
KAPPA	Saturation Field Factor
VMAX	Maximum Drift Velocity of Carriers
XJ	Metallurgical Junction Depth
UO	Surface Mobility

Transconductance Characteristic

Circuit Simulation Result

ID : Drain Current A
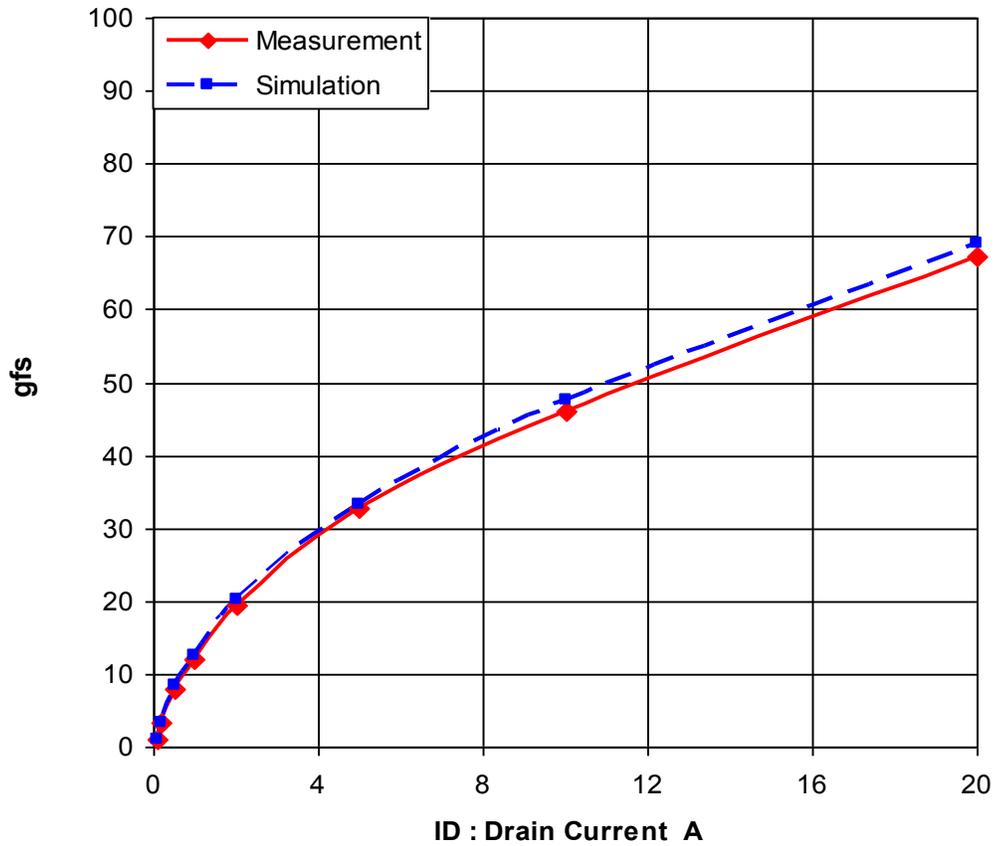
Comparison table

Id(A)	gfs		Error(%)
	Measurement	**Simulation**	
0.100	1.100	1.111	1.000
0.200	3.200	3.333	4.156
0.500	8.000	8.333	4.163
1.000	12.000	12.500	4.167
2.000	19.366	20.222	4.420
5.000	32.667	33.250	1.785
10.000	46.000	47.619	3.520
20.000	67.333	68.966	2.425

Vgs-Id Characteristic

Circuit Simulation result
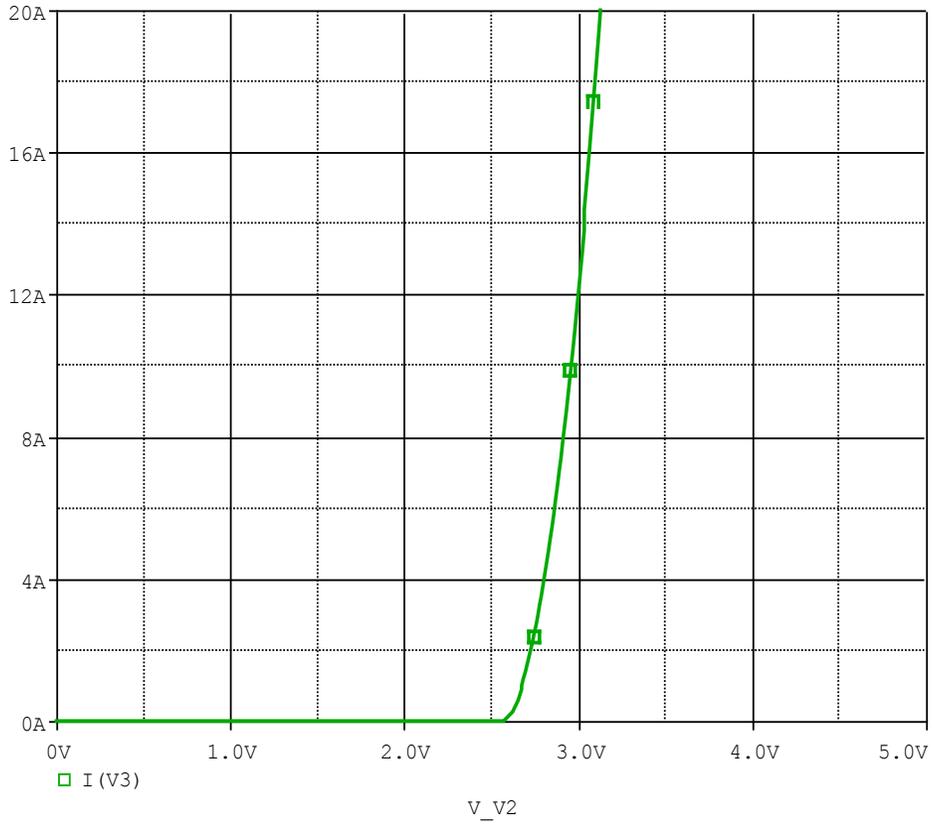
Evaluation circuit
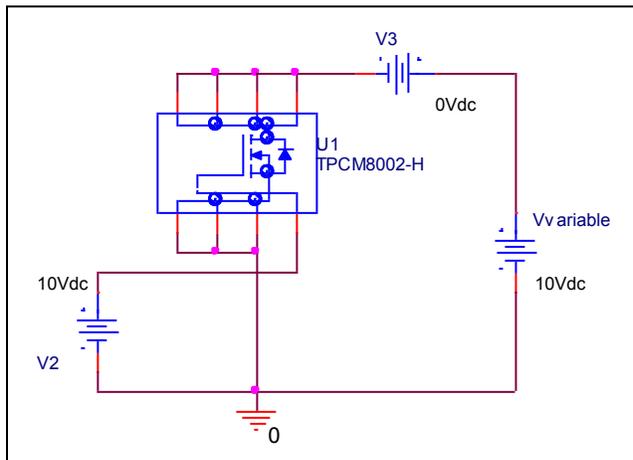
# Comparison Graph
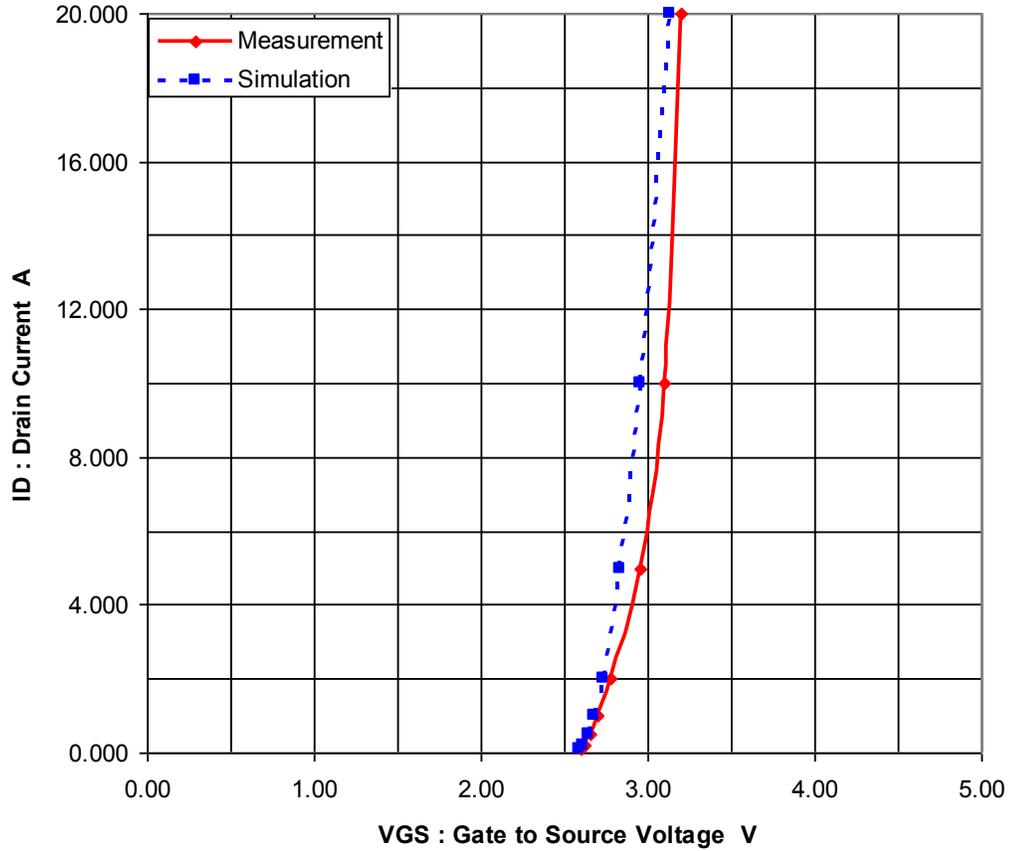
Simulation Result

$I_D(A)$	$V_{GS}(V)$		Error (%)
	Measurement	Simulation	
0.100	2.600	2.587	-0.500
0.200	2.620	2.607	-0.496
0.500	2.650	2.641	-0.340
1.000	2.700	2.678	-0.815
2.000	2.780	2.731	-1.763
5.000	2.950	2.836	-3.864
10.000	3.100	2.957	-4.613
20.000	3.200	3.131	-2.156

Rds(on) Characteristic

Circuit Simulation result
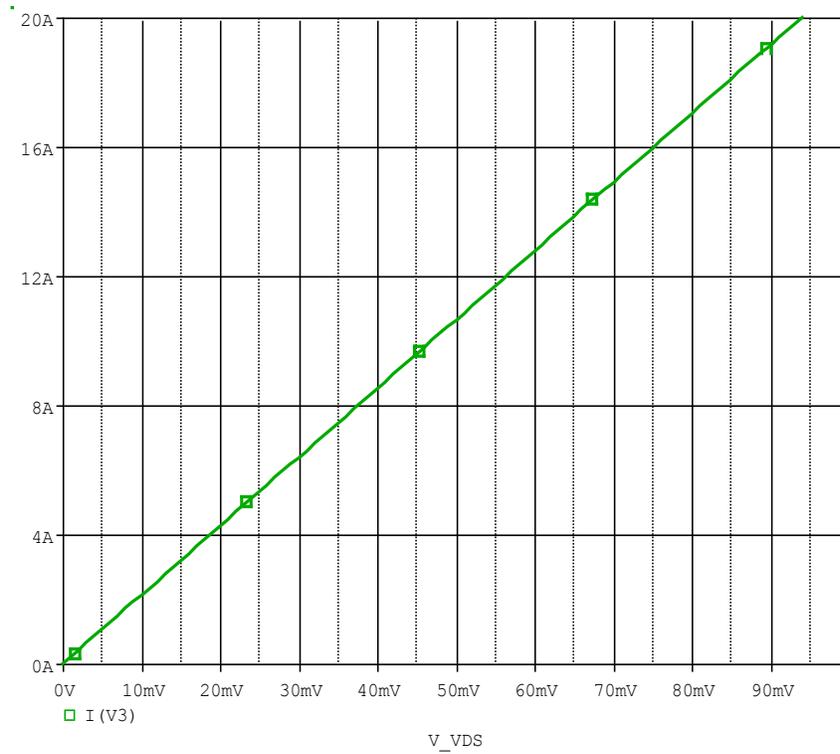
Evaluation circuit
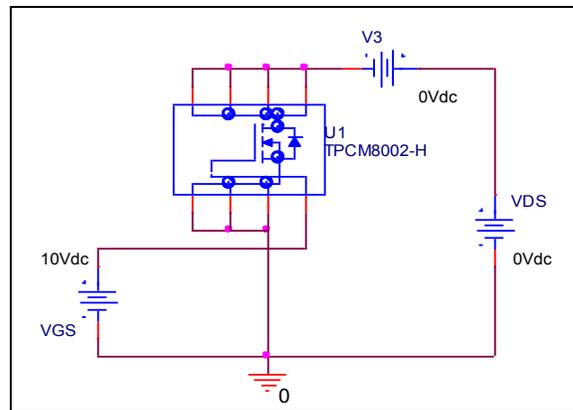
Simulation Result

I_D=15A, V_{GS}=10V	Measurement	Simulation	Error (%)
R_{DS} (on) (mΩ)	4.700	4.690	-0.213

Gate Charge Characteristic

Circuit Simulation result
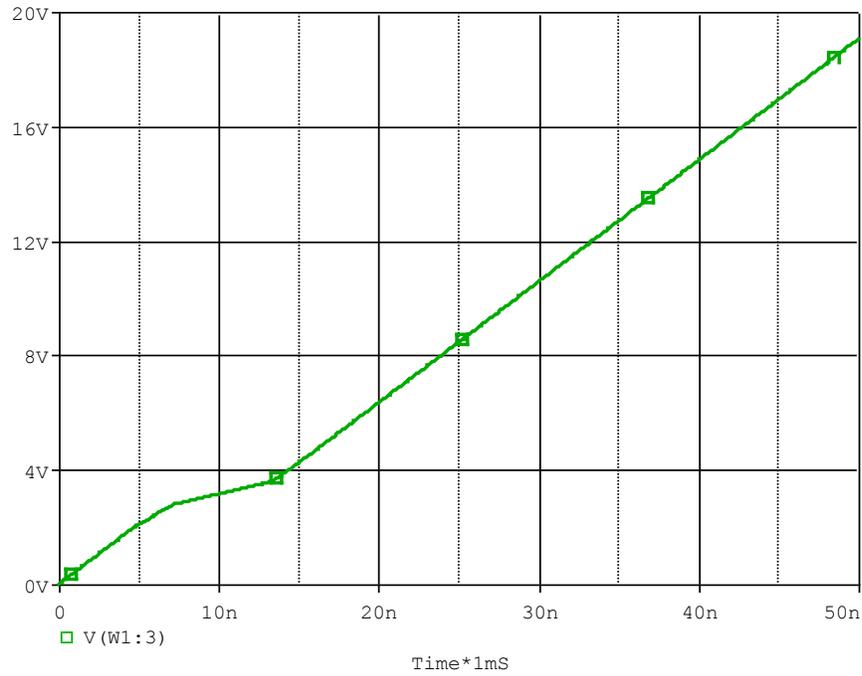
Evaluation circuit
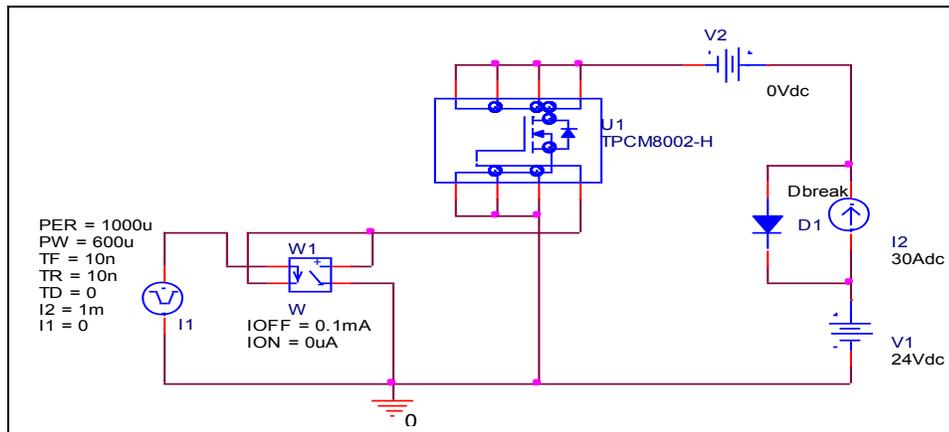
Simulation Result

V_{DD}=24V,I_D=30A ,V_{GS}=10V	Measurement	Simulation	Error (%)
Qgs(nc)	7.500	7.517	0.227
Qgd(nc)	6.000	5.931	-1.150
Qg(nc)	32.500	28.759	-11.511

Capacitance Characteristic
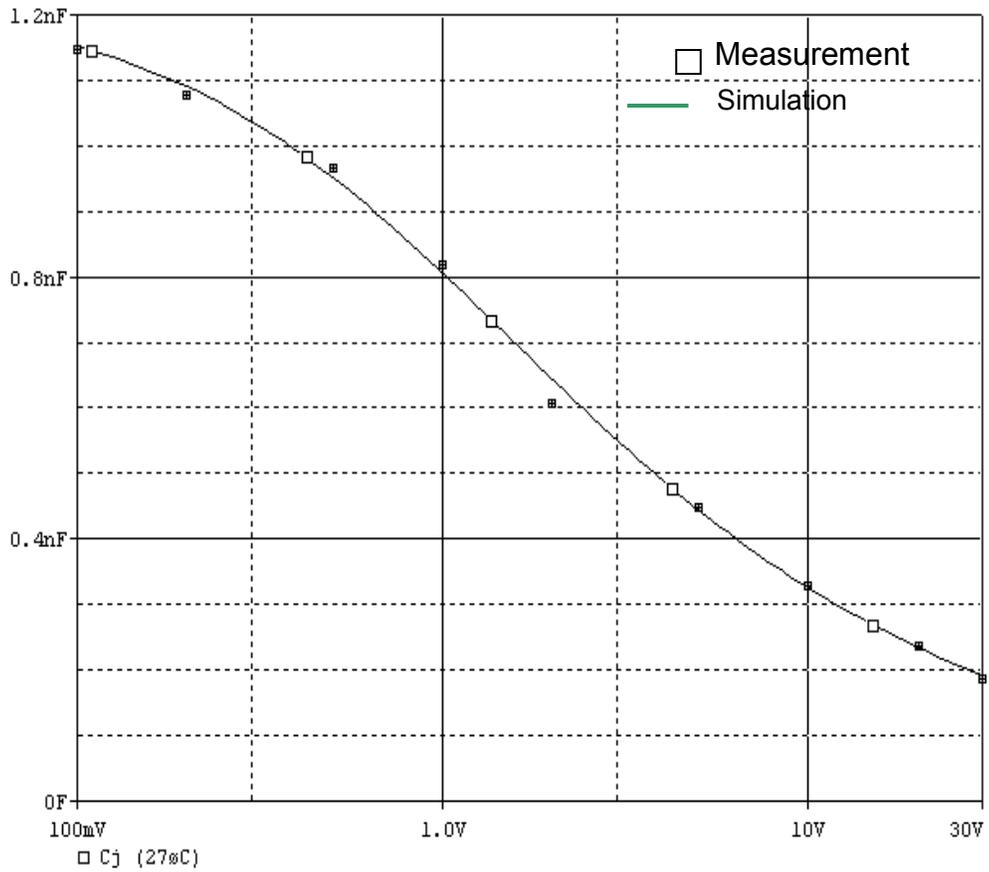
Simulation Result

V$_{DS}$(V)	Cbd(nF)		Error(%)
	Measurement	Simulation	
0.100	1.150	1.152	0.174
1.000	0.820	0.805	-1.829
10.000	0.330	0.325	-1.515
30.000	0.190	0.192	1.053

Switching Time Characteristic

Circuit Simulation result

V(2) ◇ V(3)/1.5

Time

Evaluation circuit

V1 = 0
V2 = 20
TD = 2u
TR = 6n
TF = 7n
PW = 2u
PER = 10u

R1 4.7
L1 30nH
R2 4.7
L2 50nH
RL 1
VDD 15Vdc
U1 TPCM8002-H
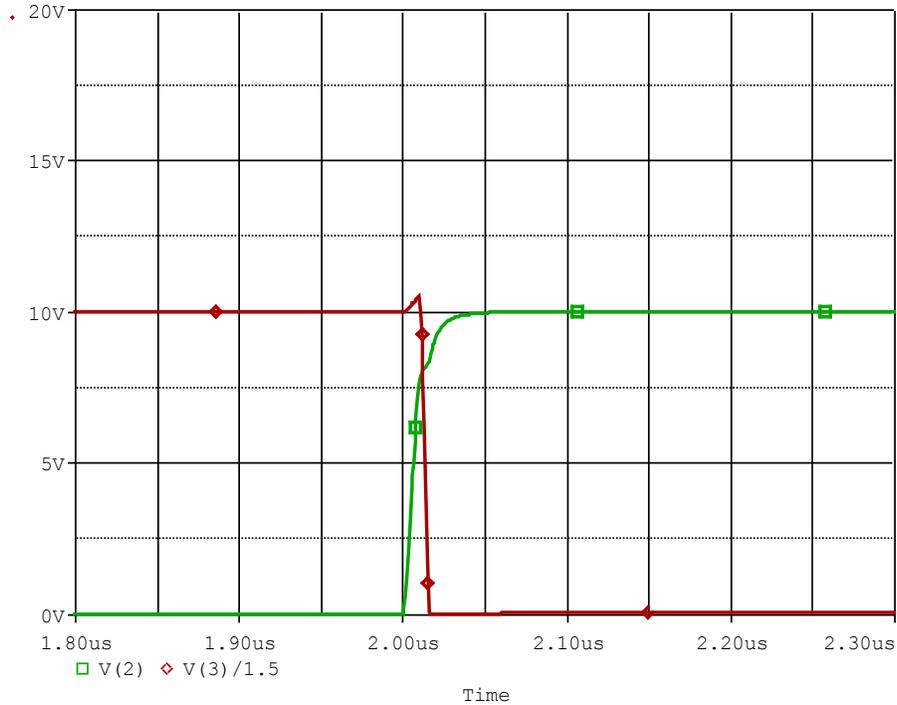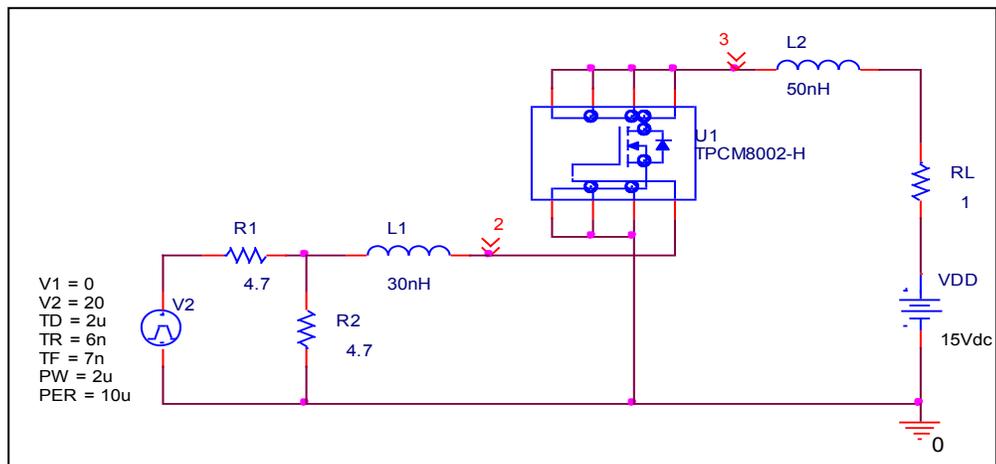
Simulation Result

I_D=15A, V_{DD}=15V V_{GS}=10V	Measurement	Simulation	Error(%)
Ton(ns)	13.000	13.096	0.738

Output Characteristic
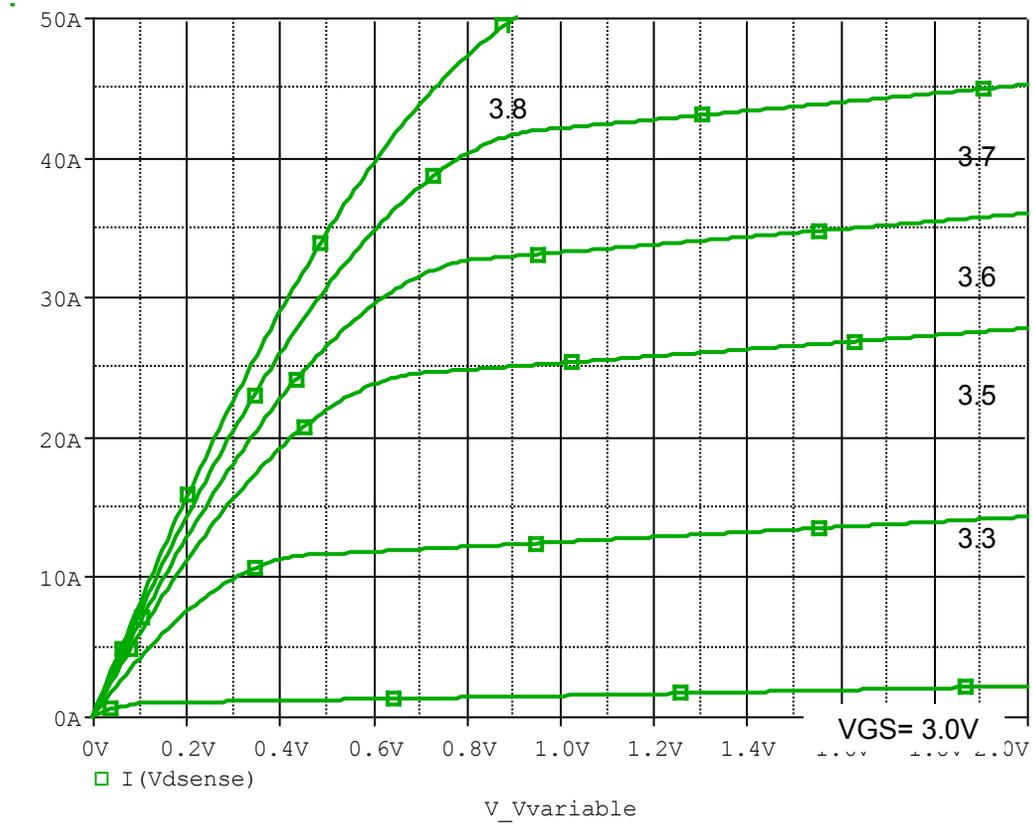
Evaluation circuit
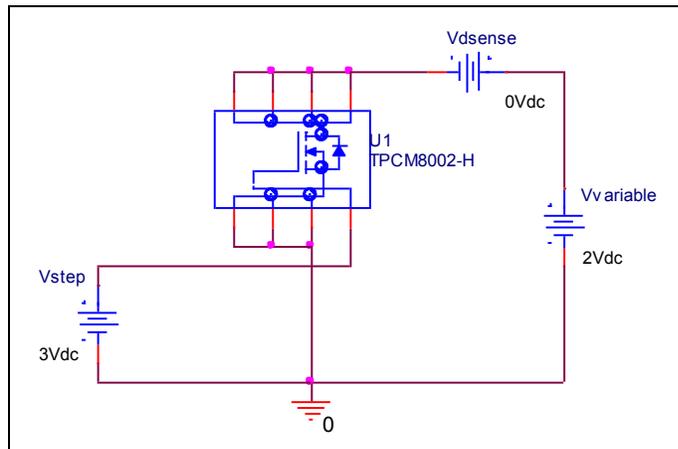
BODY DIODE SPICE MODEL
Forward Current Characteristic

□ I(R1)

V_V1

Evaluation Circuit

Vdsense

0Vdc

U1
TPCM8002-H

Vvariable

2Vdc

Vstep

3Vdc

0

Comparison Graph

Source-Drain voltage VSD(V) (x-axis)

Drain reverse current IDR(A) (y-axis)
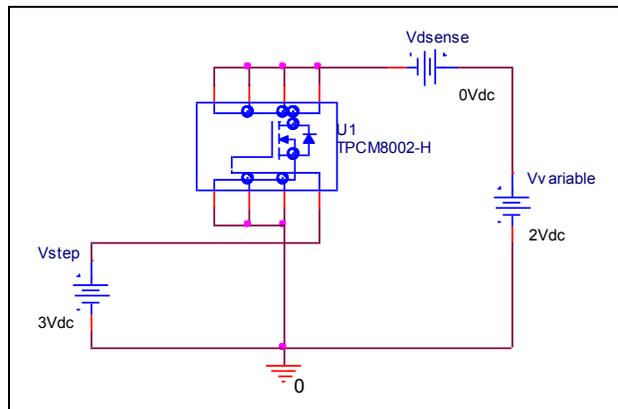
Legend: Measurement, Simulation

Simulation Result

IDR(A)	VSD(V) Measurement	VSD(V) Simulation	%Error
1.000	0.680	0.679	-0.147
2.000	0.700	0.698	-0.286
5.000	0.725	0.728	0.414
10.000	0.755	0.758	0.397
20.000	0.800	0.797	-0.375
50.000	0.870	0.872	0.230

Reverse Recovery Characteristic

Circuit Simulation Result

Evaluation Circuit

V1 = -9.4v
V2 = 10.7v
TD = 30n
TR = 10ns
TF = 10ns
PW = 20us
PER = 100us
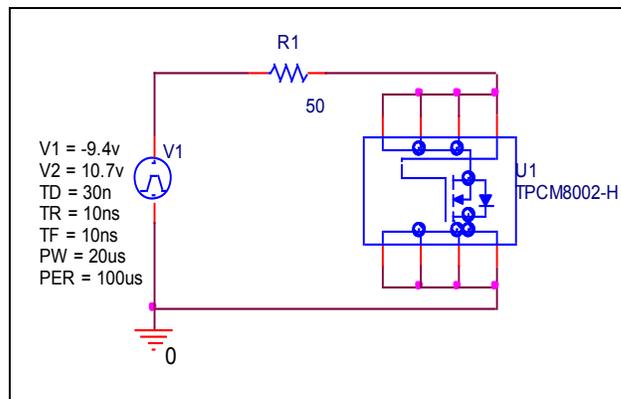
Compare Measurement vs. Simulation

	Measurement	Simulation	Error (%)
Trj(ns)	20.800	20.604	-0.942

Reverse Recovery Characteristic

| Ch2 | 2.50 V | M 40.0ns | A | Ch2 ↲ −900mV |
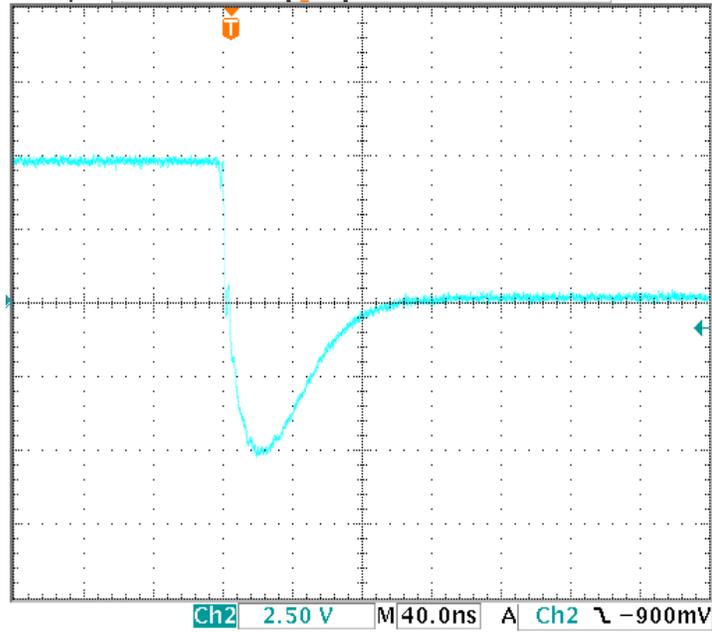
Trj= 20.8 (ns)
Trb= 54.4 (ns)
Conditions:Ifwd=Irev=0.2(A),Rl=50
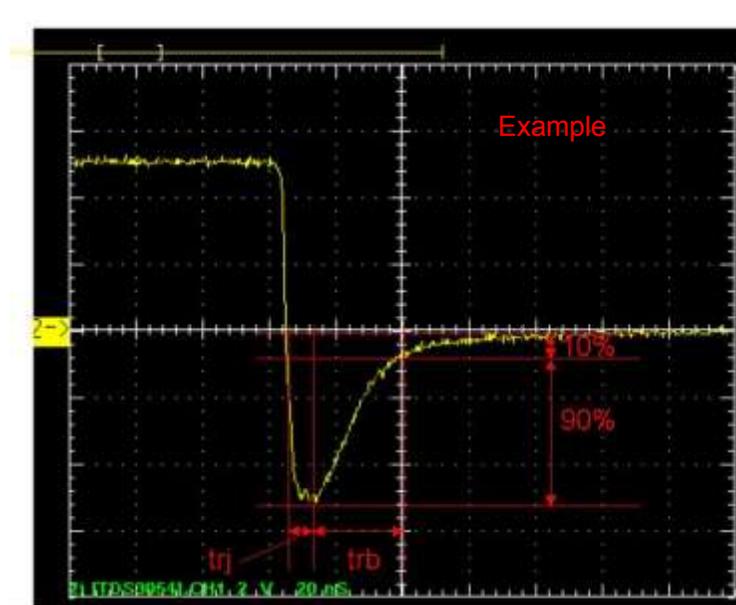
Relation between trj and trb